Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards Phone - Representative* Email - Representative* Email - Representative* Phone - Representative* Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards	OLATION CONTROL (	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name   Com						*					ials and Mf	g Informat	ion		
Insemi  Insemi	olier Informat	ion				·									
Product Env-Stewards	Company name*				Company unique ID			Unique ID Authority				Response Date*			
Product Env-Stewards Authorized Representative* Title - Representative Product Env-Stewards	ni											2025-06-	07		
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Numbe	act Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  S1MFL SR SOD123HE GPPN 1A 1000V 2025-06-07 TSCBE 15.0 mg  Manufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM  Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM  Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Scomments	uct-Env-Stewards	s		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*			
SIMFL   SR SOD123HE GPPN 1A 1000V   2025-06-07   TSCBE   15.0   mg	Product-Env-Stewards				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester It	tem Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Ianufacturing Site	V	/eight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  Comments			S1MFL		SR SOD123HE GP	PPN 1A 1000V	V	2025-06-07		Т	SCBE	1.	5.0	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Reso	Alloy	STD 020 MS	I. Poting	Dank Denog	es Rody To	mparatur	May Time at Pook	Tamparatu	ra Numi	per of Paflow Cyc	lac
omments					Alloy J-	31D-020 MSI	L Kating		ess body Te	•				ber of Kellow Cyc	ies
	•	511) - alillealeu	C	O Alloy	1			200		<u> </u>	30	second	s  3		
		a at neak temperatur	a dunina1	domina ia 10-2	10 seconds										
or more information regarding material composition please refer to page 3															

<b>RoHS Material Composition Declaration</b>			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provid										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	1.52	mg	Supplier	Copper (Cu)	7440-50-8		1.52	mg
Die	0.997	mg	Supplier	Silicon (Si)	7440-21-3		0.8973	mg
			В	Nickel (Ni)	7440-02-0		0.0065	mg
			Supplier	Gold (Au)	7440-57-5		0.0015	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0917	mg
Die Attach Solder	0.408	mg	Supplier	Silver (Ag)	7440-22-4		0.0102	mg
			A	Lead (Pb)	7439-92-1	7a	0.3774	mg
			Supplier	Tin (Sn)	7440-31-5		0.0204	mg
Lead Frame	5.584	mg	Supplier	Iron (Fe)	7439-89-6		0.0056	mg
			Supplier	Copper (Cu)	7440-50-8		5.5767	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0017	mg
Mold Compound-Black	6.292	mg		Epoxy resin	proprietary data		0.3146	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1258	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1573	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0315	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.6628	mg
Plating	0.199	mg	Supplier	Tin (Sn)	7440-31-5		0.199	mg